Wide Temperature Range Version 4M High Speed SRAM (256-kword × 16-bit)

HITACHI

ADE-203-1263A (Z)

Rev. 1.0 Nov. 1, 2001

Description

The HM62W16255HCI is a 4-Mbit high speed static RAM organized 256-kword \times 16-bit. It has realized high speed access time by employing CMOS process (6-transistor memory cell) and high speed circuit designing technology. It is most appropriate for the application which requires high speed, high density memory and wide bit width configuration, such as cache and buffer memory in system. The HM62W16255HCI is packaged in 400-mil 44-pin SOJ and 400-mil 44-pin plastic TSOPII for high density surface mounting.

Features

• Single 3.3 V supply: $3.3 \text{ V} \pm 0.3 \text{ V}$

• Access time: 12 ns (max)

• Completely static memory

- No clock or timing strobe required

• Equal access and cycle times

• Directly TTL compatible

— All inputs and outputs

• Operating current: 130 mA (max)

• TTL standby current: 40 mA (max)

• CMOS standby current: 5 mA (max)

• Center V_{CC} and V_{ss} type pinout

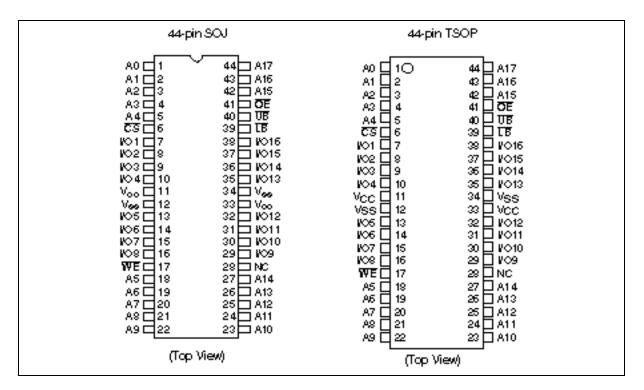
• Temperature range: -40 to +85°C



Ordering Information

Type No.	Access time	Device marking	Package
HM62W16255HCJPI-12	12 ns	HM62W16255CJPI12	400-mil 44-pin plastic SOJ (CP-44D)
HM62W16255HCTTI-12	12 ns	HM62W16255CTTI12	400-mil 44-pin plastic TSOPII (TTP-44DE)

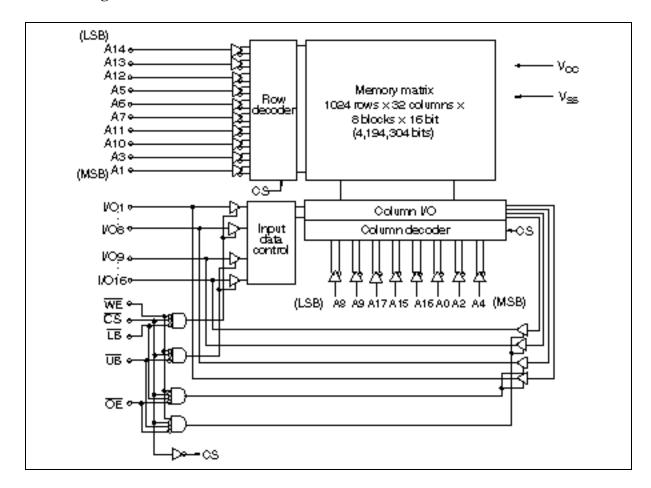
Pin Arrangement



Pin Description

Pin name	Function
A0 to A17	Address input
I/O1 to I/O16	Data input/output
CS	Chip select
OE	Output enable
WE	Write enable
UB	Upper byte select
LB	Lower byte select
V _{cc}	Power supply
V _{ss}	Ground
NC	No connection

Block Diagram



Operation Table

CS	OE	WE	LB	UB	Mode	V_{cc} current	I/O1–I/O8	I/O9-I/O16	Ref. cycle
Н	×	×	×	×	Standby	I _{SB} , I _{SB1}	High-Z	High-Z	_
L	Н	Н	×	×	Output disable	I _{cc}	High-Z	High-Z	_
L	L	Н	L	L	Read	I _{cc}	Output	Output	Read cycle
L	L	Н	L	Н	Lower byte read	I _{cc}	Output	High-Z	Read cycle
L	L	Н	Н	L	Upper byte read	I _{cc}	High-Z	Output	Read cycle
L	L	Н	Н	Н	_	I _{cc}	High-Z	High-Z	_
L	×	L	L	L	Write	I _{cc}	Input	Input	Write cycle
L	×	L	L	Н	Lower byte write	I _{cc}	Input	High-Z	Write cycle
L	×	L	Н	L	Upper byte write	I _{cc}	High-Z	Input	Write cycle
L	×	L	Н	Н	_	I _{cc}	High-Z	High-Z	_

Note: H: V_{IH} , L: V_{IL} , \times : V_{IH} or V_{IL}

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply voltage relative to V _{ss}	V _{cc}	-0.5 to +4.6	V
Voltage on any pin relative to V _{ss}	V _T	-0.5^{*1} to $V_{cc} + 0.5^{*2}$	V
Power dissipation	P _T	1.0	W
Operating temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +125	°C
Storage temperature under bias	Tbias	-40 to +85	°C

Notes: 1. V_{T} (min) = -2.0 V for pulse width (under shoot) \leq 6 ns

2. $V_{_{T}}$ (max) = $V_{_{CC}}$ + 2.0 V for pulse width (over shoot) \leq 6 ns

Recommended DC Operating Conditions

 $(Ta = -40 \text{ to } +85^{\circ}C)$

Parameter	Symbol	Min	Тур	Max	Unit
Supply voltage	V _{cc} *3	3.0	3.3	3.6	V
	V _{SS} *4	0	0	0	V
Input voltage	V _{IH}	2.0	_	V _{cc} + 0.5*2	V
	V _{IL}	-0.5* ¹	_	0.8	V

Notes: 1. V_{ii} (min) = -2.0 V for pulse width (under shoot) \leq 6 ns

- 2. V_{IH} (max) = V_{CC} + 2.0 V for pulse width (over shoot) \leq 6 ns
- 3. The supply voltage with all $\rm V_{\rm cc}$ pins must be on the same level.
- 4. The supply voltage with all $V_{\rm ss}$ pins must be on the same level.

DC Characteristics

 $(Ta = -40 \text{ to } +85^{\circ}\text{C}, V_{cc} = 3.3 \text{ V} \pm 0.3 \text{ V}, V_{ss} = 0 \text{ V})$

Parameter	Symbol	Min	Typ*1	Max	Unit	Test conditions
Input leakage current	I _{LI}	_	_	2	μΑ	$Vin = V_{ss} to V_{cc}$
Output leakage current	I _{LO}	_	_	2	μΑ	$Vin = V_{ss} to V_{cc}$
Operating power supply current	I _{cc}	_	_	130	mA	Min cycle $CS = V_{IL}$, lout = 0 mA Other inputs = V_{IH}/V_{IL}
Standby power supply current	l _{SB}	_	_	40	mA	Min cycle, $CS = V_{IH}$, Other inputs $= V_{IH}/V_{IL}$
	I _{SB1}	_	2.5	5	mA	$ f = 0 \text{ MHz} $ $V_{\infty} \ge CS \ge V_{\infty} - 0.2 \text{ V}, $ $(1) 0 V \le V \text{in} \le 0.2 \text{ V or} $ $(2) V_{\infty} \ge V \text{in} \ge V_{\infty} - 0.2 \text{ V} $
Output voltage	V _{OL}	_	_	0.4	V	$I_{OL} = 8 \text{ mA}$
	V _{OH}	2.4	_	_	V	I _{OH} = -4 mA

Notes: 1. Typical values are at $V_{cc} = 3.3 \text{ V}$, $Ta = +25^{\circ}\text{C}$ and not guaranteed.

Capacitance

 $(Ta = +25^{\circ}C, f = 1.0 \text{ MHz})$

Parameter	Symbol	Min	Тур	Max	Unit	Test conditions
Input capacitance*1	Cin	_	_	6	pF	Vin = 0 V
Input/output capacitance*1	C _{I/O}	_	_	8	pF	V _{I/O} = 0 V

Note: 1. This parameter is sampled and not 100% tested.

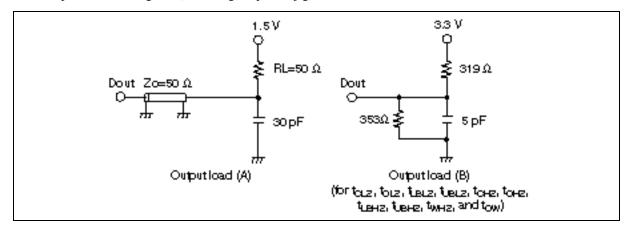
AC Characteristics

(Ta = -40 to +85 °C, V_{cc} = 3.3 V \pm 0.3 V, unless otherwise noted.)

Test Conditions

Input pulse levels: 3.0 V/0.0 V
Input rise and fall time: 3 ns

Input and output timing reference levels: 1.5 V
Output load: See figures (Including scope and jig)



Read Cycle

HM62W16255HCI

		-12			
Parameter	Symbol	Min	Max	Unit	Notes
Read cycle time	t _{RC}	12	_	ns	
Address access time	t _{AA}	_	12	ns	
Chip select access time	t _{ACS}	_	12	ns	
Output enable to output valid	t _{oe}	_	6	ns	
Byte select to output valid	t_{LB} , t_{UB}	_	6	ns	
Output hold from address change	t _{oh}	3	_	ns	
Chip select to output in low-Z	t _{cLZ}	3	_	ns	1
Output enable to output in low-Z	t _{oLZ}	0	_	ns	1
Byte select to output in low-Z	t_{LBLZ},t_{UBLZ}	0	_	ns	1
Chip deselect to output in high-Z	t _{chz}	_	6	ns	1
Output disable to output in high-Z	t _{ohz}	_	6	ns	1
Byte deselect to output in high-Z	$t_{\rm LBHZ},t_{\rm UBHZ}$	_	6	ns	1

Output disable to output in high-Z

Write enable to output in high-Z

HM62W16255HCI Series

1

1

ns

ns

HM62W16255HCI

6

6

Write Cycle

		11111021	102001101		
		-12			
Parameter	Symbol	Min	Max	Unit	Notes
Write cycle time	t _{wc}	12	_	ns	
Address valid to end of write	t _{AW}	8	_	ns	
Chip select to end of write	t _{cw}	8	_	ns	8
Write pulse width	t _{wP}	8	_	ns	7
Byte select to end of write	$\mathbf{t}_{LBW},\mathbf{t}_{UBW}$	8	_	ns	9, 10
Address setup time	t _{AS}	0	_	ns	5
Write recovery time	t _{wR}	0	_	ns	6
Data to write time overlap	t _{DW}	6	_	ns	
Data hold from write time	t _{DH}	0	_	ns	
Write disable to output in low-Z	t _{ow}	3	_	ns	1

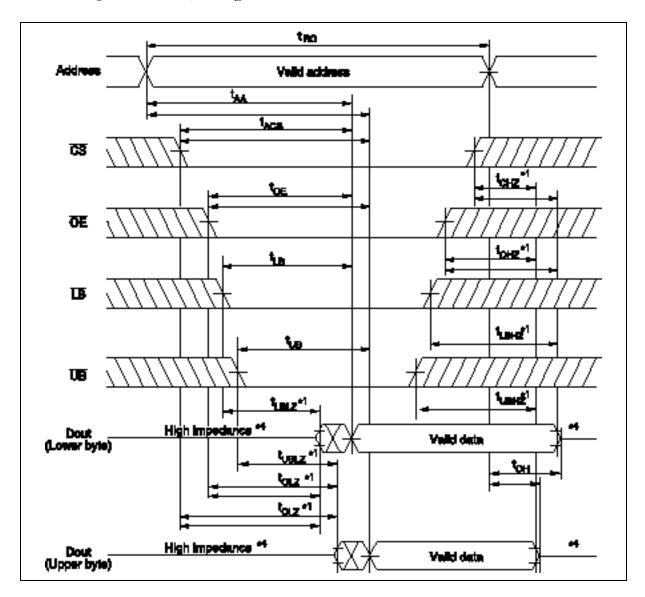
Notes: 1. Transition is measured ±200 mV from steady voltage with output load (B). This parameter is sampled and not 100% tested.

 $\mathbf{t}_{\mathsf{WHZ}}$

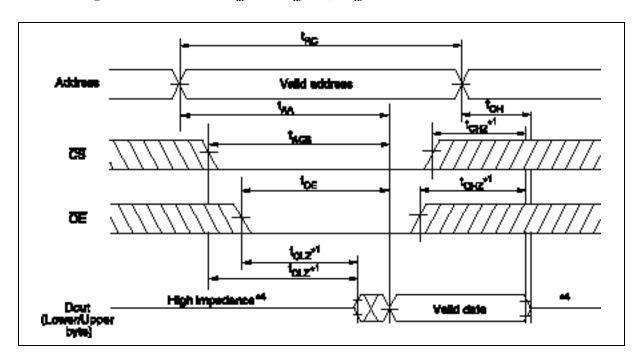
- 2. If the CS or LB or UB low transition occurs simultaneously with the WE low transition or after the WE transition, output remains a high impedance state.
- 3. WE and/or CS must be high during address transition time.
- 4. If CS, OE, LB and UB are low during this period, I/O pins are in the output state. Then the data input signals of opposite phase to the outputs must not be applied to them.
- 5. t_{as} is measured from the latest address transition to the latest of CS, WE, LB or UB going low.
- 6. t_{ws} is measured from the earliest of CS, WE, LB or UB going high to the first address transition.
- 7. A write occurs during the overlap of low CS, low WE and low LB or low UB.
- 8. t_{cw} is measured from the later of CS going low to the end of write.
- 9. t_{LBW} is measured from the later of LB going low to the end of write.
- 10. t_{UBW} is measured from the later of UB going low to the end of write.

Timing Waveforms

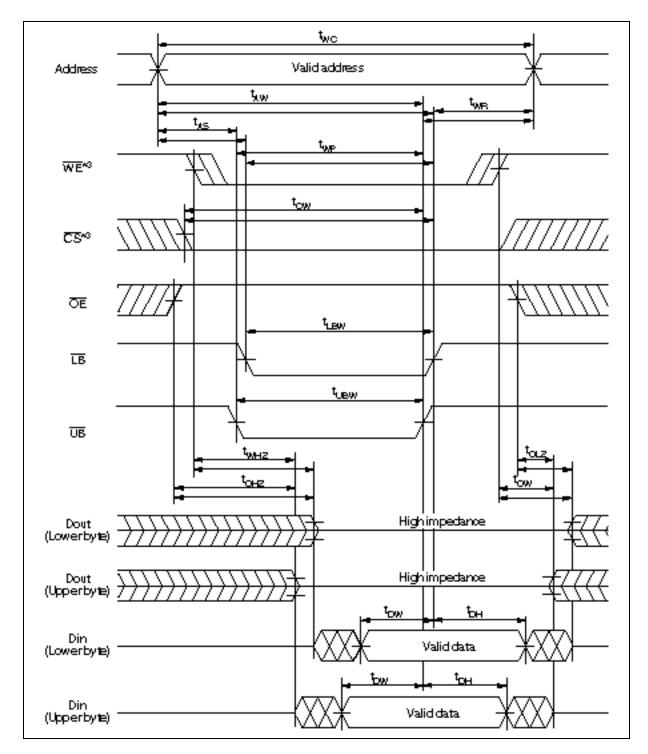
Read Timing Waveform (1) (WE = $V_{\text{\tiny IH}}$)



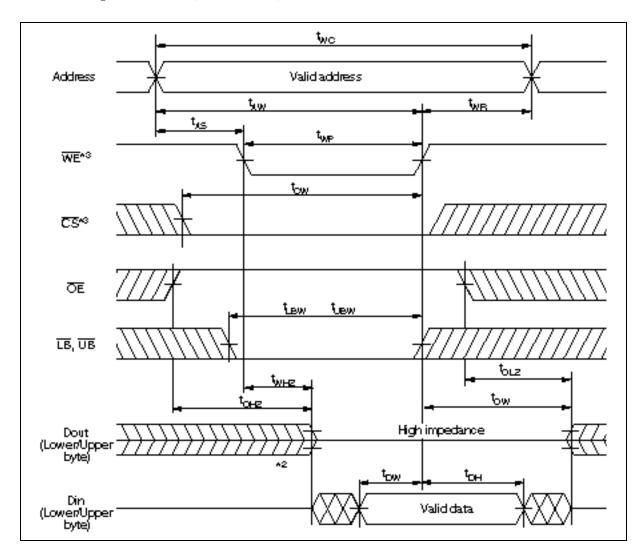
Read Timing Waveform (2) (WE = $V_{_{I\!I\!I}},$ LB = $V_{_{I\!L}},$ UB , = $V_{_{I\!L}})$



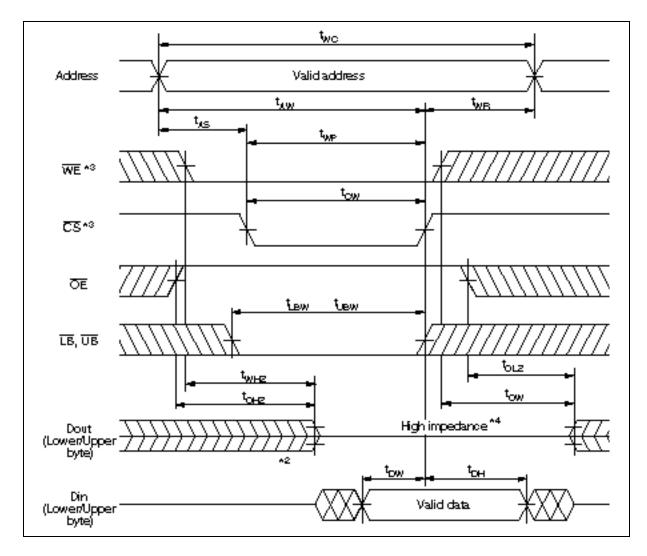
Write Timing Waveform (1) (LB, UB Controlled)



Write Timing Waveform (2) (WE Controlled)

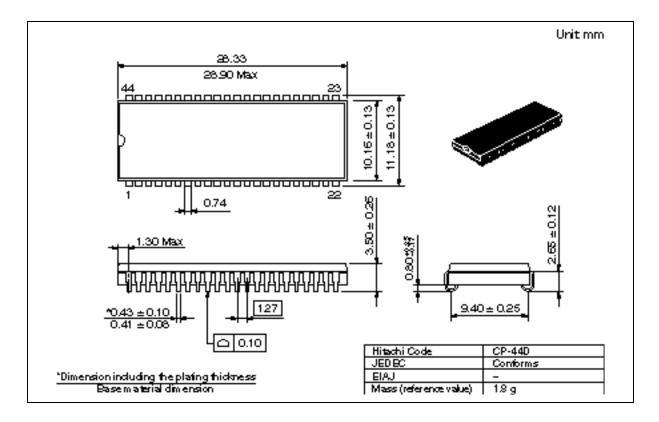


Write Timing Waveform (3) (CS Controlled)

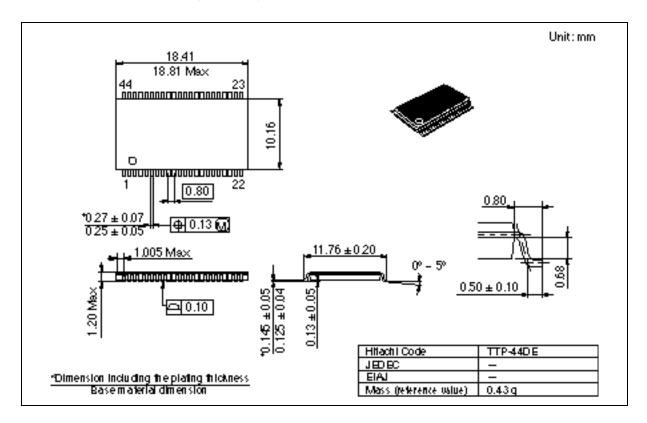


Package Dimensions

HM62W16255HCJPI Series (CP-44D)



HM62W16255HCTTI Series (TTP-44DE)



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